

AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows.

Please replace the first full paragraph on page 16 (starting with the words "The rigid and resilient elements") with the following paragraph.

B¹
The rigid and resilient elements, 128 and 126, combine to provide a backing in the form of a back-up pad 118 (Figure 4) attached to support layer 112 of the fixed abrasive composites 103 ~~113~~ on the polishing layer 100. The back-up pad 118 is described in detail in United States Patent No. 6,007,407 to Rutherford et al., the disclosure on which is incorporated by reference herein. During an ECMD process, the second backing surface 124 of the resilient element 126 may be attached to the platen of an ECMD apparatus. In operation, the surfaces 105 of the fixed abrasive elements 103 normally contact the semiconductor wafer workpiece.

Please replace the paragraph bridging pages 16 and 17 (starting with the words "Referring to Figure 5") with the following paragraph.

B²
Referring to Figure 5, rigid element 128 of backing 118 comprises second channels 130 extending from a central portion, generally indicated at 132, and terminating near the edges 134 of the element 128. Each of the second channels 130 comprise a series of flow apertures 140 aligned in a discernable progression, extending through the element 128 and aligned with and coextensive with the first channels 104 of the polishing layer 100. As shown in Figure 6, the resilient element 126 of the backing 118 also includes a plurality of second channels 142 extending from a central portion, generally indicated at 144 of the resilient ~~rigid~~ element 126, and terminating near the edges 146. Each of the second channels 142 comprises a series of flow apertures 148 extending through the resilient element 126 and positioned to be coextensive with the second channel flow apertures 140 of the rigid element 128. The flow apertures 148 of the channels 142 on resilient element 126 are connected to one another along elongate channel components 150. The rigid element 128 is positioned between the resilient element 126 and the polishing layer 100, and the three layers are adhesively affixed to one another using a suitable PSA such as those available as 3M 9671LE and 3M 9471FL, described above.